



REF3112 REF3125 REF3130 REF3133 REF3140

SBVS046C - DECEMBER 2003 - REVISED FEBRUARY 2006

# 15ppm/°C Max, 100μA, SOT23-3 SERIES VOLTAGE REFERENCE

## **FEATURES**

● MicroSIZE PACKAGE: SOT23-3

● LOW DROPOUT: 5mV

● HIGH OUTPUT CURRENT: ±10mA

● HIGH ACCURACY: 0.2% max

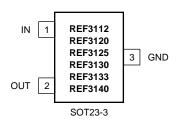
• LOW Io: 115μA max

• EXCELLENT SPECIFIED DRIFT PERFORMANCE:

15ppm/°C (max) from 0°C to +70°C 20ppm/°C (max) from -40°C to +125°C

## **APPLICATIONS**

- PORTABLE, BATTERY-POWERED EQUIPMENT
- DATA ACQUISITION SYSTEMS
- MEDICAL EQUIPMENT
- HAND-HELD TEST EQUIPMENT



## DESCRIPTION

The REF31xx is a family of precision, low power, low dropout, series voltage references available in the tiny SOT23-3 package.

The REF31xx's small size and low power consumption ( $100\mu A$  typ) make it ideal for portable and battery-powered applications. The REF31xx does not require a load capacitor, but is stable with any capacitive load and can sink/source up to 10mA of output current.

Unloaded, the REF31xx can be operated on supplies down to 5mV above the output voltage. All models are specified for the wide temperature range of  $-40^{\circ}$ C to  $+125^{\circ}$ C.

PRODUCT	VOLTAGE (V)
REF3112	1.25
REF3120	2.048
REF3125	2.5
REF3130	3.0
REF3133	3.3
REF3140	4.096



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#### ABSOLUTE MAXIMUM RATINGS(1)

7.0V
Continuous
55°C to +135°C
65°C to +150°C
+150°C

NOTES: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these, or any other conditions beyond those specified, is not implied.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### PACKAGE/ORDERING INFORMATION(1)

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
REF3112	SOT23-3	DBZ "	-40°C to +125°C	R31A "	REF3112AIDBZT REF3112AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF3120	SOT23-3	DBZ "	-40°C to +125°C	R31B "	REF3120AIDBZT REF3120AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF3125	SOT23-3	DBZ "	-40°C to +125°C	R31C "	REF3125AIDBZT REF3125AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF3130	SOT23-3	DBZ "	-40°C to +125°C	R31E "	REF3130AIDBZT REF3130AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF3133	SOT23-3	DBZ "	-40°C to +125°C	R31F "	REF3133AIDBZT REF3133AIDBZR	Tape and Reel, 250 Tape and Reel, 3000
REF3140	SOT23-3	DBZ "	-40°C to +125°C	R31D "	REF3140AIDBZT REF3140AIDBZR	Tape and Reel, 250 Tape and Reel, 3000

NOTE: (1) (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www ti com

## **ELECTRICAL CHARACTERISTICS**

**Boldface** limits apply over the specified temperature range,  $T_A = -40^{\circ}C$  to  $+125^{\circ}C$ .

At  $T_A = +25$ °C,  $I_{LOAD} = 0$ mA,  $V_{IN} = 5$ V, unless otherwise noted.

				REF31xx			
PARAMETER		CONDITIONS	MIN	TYP	MAX	UNITS	
	· ·	REF3112 <sup>(1)</sup> - 1.25	/				
OUTPUT VOLTAGE Initial Accuracy	V <sub>OUT</sub>		1.2475 -0.2	1.25	1.2525 0.2	V %	
NOISE Output Voltage Noise Voltage Noise		f = 0.1Hz to 10Hz f = 10Hz to 10kHz		17 24		μV <sub>PP</sub> μVrms	
		REF3120 - 2.048				Γ	
OUTPUT VOLTAGE Initial Accuracy	V <sub>OUT</sub>		2.0439 -0.2	2.048	2.0521 0.2	V %	
NOISE Output Voltage Noise Voltage Noise		f = 0.1Hz to 10Hz f = 10Hz to 10kHz		27 39		μV <sub>PP</sub> μVrms	
		REF3125 - 2.5V					
OUTPUT VOLTAGE Initial Accuracy	V <sub>OUT</sub>		2.4950 -0.2	2.50	2.5050 0.2	V %	
NOISE Output Voltage Noise Voltage Noise		f = 0.1Hz to 10Hz f = 10Hz to 10kHz		33 48		μV <sub>PP</sub> μVrms	

## **ELECTRICAL CHARACTERISTICS**

**Boldface** limits apply over the specified temperature range,  $T_A = -40^{\circ}C$  to  $+125^{\circ}C$ .

At  $T_A$  = +25°C,  $I_{LOAD}$  = 0mA,  $V_{IN}$  = +5V, unless otherwise noted.

				REF31xx				
PARAMETER		CONDITIONS	MIN	TYP	MAX	UNITS		
		REF3130 - 3.0V						
OUTPUT VOLTAGE Initial Accuracy	V <sub>OUT</sub>		2.9940 -0.2	3.0	3.0060 0.2	V %		
NOISE Output Voltage Noise Voltage Noise		f = 0.1Hz to 10Hz f = 10Hz to 10kHz		39 57		μV <sub>PP</sub> μVrms		
	L	REF3133 - 3.3V				F		
OUTPUT VOLTAGE Initial Accuracy	V <sub>OUT</sub>		3.2934 -0.2	3.30	3.3066 0.2	V %		
NOISE Output Voltage Noise Voltage Noise		f = 0.1Hz to 10Hz f = 10Hz to 10kHz		43 63		μV <sub>PP</sub> μVrms		
		REF3140 - 4.096V						
OUTPUT VOLTAGE Initial Accuracy	V <sub>OUT</sub>		4.0878 -0.2	4.096	4.1042 0.2	V %		
NOISE Output Voltage Noise Voltage Noise		f = 0.1Hz to 10Hz f = 10Hz to 10kHz		53 78		μV <sub>PP</sub> μVrms		
F	REF3112, REF	3120, REF3125, REF3130, REF	3133, REF314	0				
OUTPUT VOLTAGE TEMP DRIF	<b>T</b> <sup>(2)</sup> dV <sub>OUT</sub> /dT	$0^{\circ}$ C $\leq$ T <sub>A</sub> $\leq$ +70 $^{\circ}$ C -40 $^{\circ}$ C $\leq$ T <sub>A</sub> $\leq$ +125 $^{\circ}$ C		5 10	15 20	ppm/°C ppm/°C		
LONG-TERM STABILITY		······································						
LINE REGULATION	+	$\frac{\text{0-1000h}}{\text{V}_{\text{REF}} + 0.05^{(1)} \le \text{V}_{\text{IN}} \le 5.5\text{V}}$		70 20	65	ppm ppm/V		
LOAD REGULATION <sup>(3)</sup> Sourcing Sinking	dV <sub>OUT</sub> /dI <sub>LOAD</sub>	$0mA < I_{LOAD} < 10mA,$ $V_{IN} = V_{REF} + 250mV^{(1)}$ $-10mA < I_{LOAD} < 0mA,$ $V_{IN} = V_{REF} + 100mV^{(1)}$		10	30 50	μV/mA μV/mA		
THERMAL HYSTERESIS <sup>(4)</sup> First Cycle Additional Cycles		dT		100 25		ppm ppm		
DROPOUT VOLTAGE(1)	V <sub>IN</sub> - V <sub>OUT</sub>			5	50	mV		
OUTPUT CURRENT	I <sub>LOAD</sub>		-10		10	mA		
SHORT-CIRCUIT CURRENT Sourcing Sinking	I <sub>sc</sub>			50 40		mA mA		
TURN-ON SETTLING TIME		to 0.1% at $V_{IN}$ = +5V with $C_L$ = 0		400		μs		
POWER SUPPLY Voltage Quiescent Current Over Temperature	V <sub>s</sub>	I <sub>L</sub> = 0	V <sub>REF</sub> + 0.05 <sup>(1)</sup>	100 <b>115</b>	<b>5.5</b> 115 <b>135</b>	<b>V</b> μΑ μ <b>A</b>		
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance SOT23-3 Surface-Mount	$ heta_{ exttt{JA}}$		-40 -55 -65	336	+125 +135 +150	, , , , ,		

NOTES: (1) Minimum supply voltage for REF3112 is 1.8V.



<sup>(2)</sup> Box Method used to determine temperature drift.

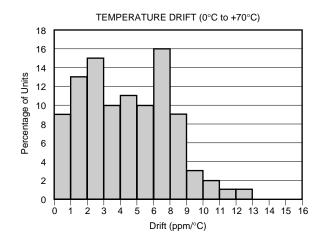
<sup>(3)</sup> Typical value of load regulation reflects measurements using force and sense contacts; see the Load Regulation section.

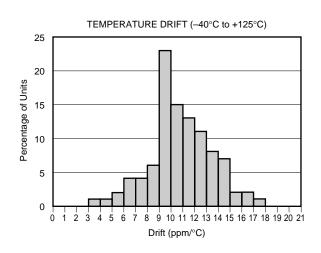
 $<sup>(4) \</sup> Thermal \ hysteres is \ explained \ in \ more \ detail \ in \ the \ \textit{Applications Information} \ section \ of \ this \ data \ sheet.$ 

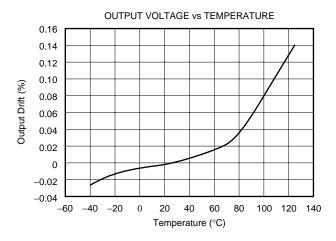
<sup>(5)</sup> For  $I_L > 0$ , see the Typical Characteristic curves.

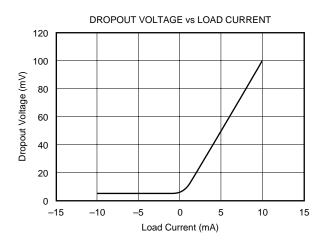
## TYPICAL CHARACTERISTICS

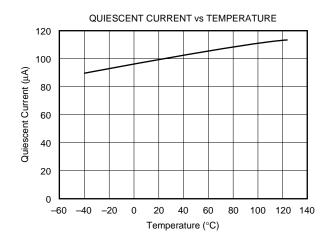
At  $T_A = +25$ °C,  $V_{IN} = +5$ V power supply, REF3125 is used for typical characteristics, unless otherwise noted.

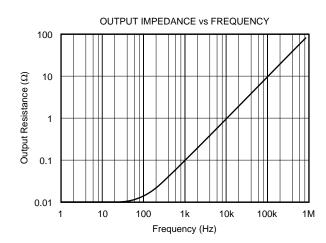






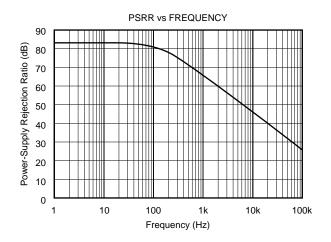


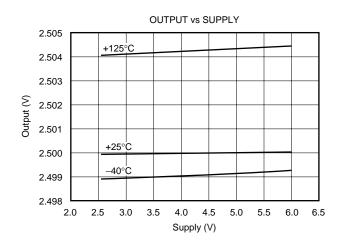


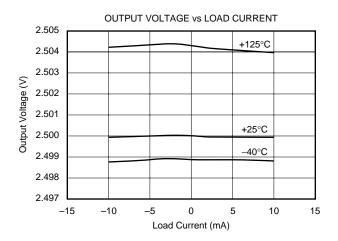


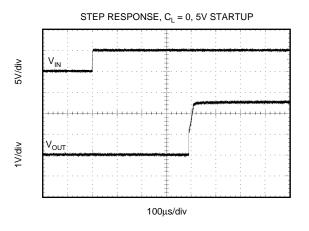
# **TYPICAL CHARACTERISTICS (Cont.)**

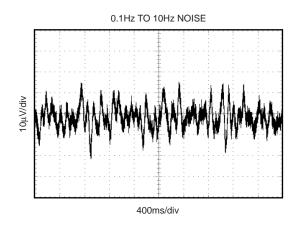
At  $T_A = +25$ °C,  $V_{IN} = +5$ V power supply, REF3125 is used for typical characteristics, unless otherwise noted.

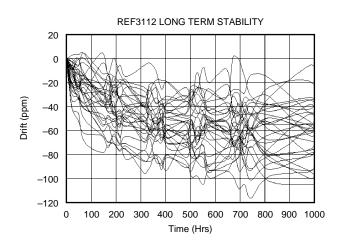






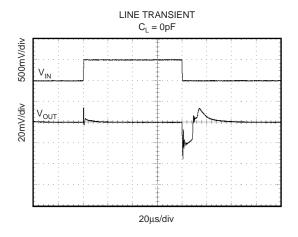


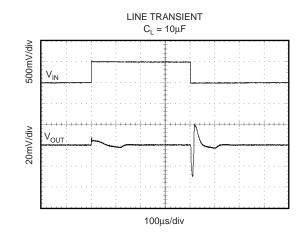


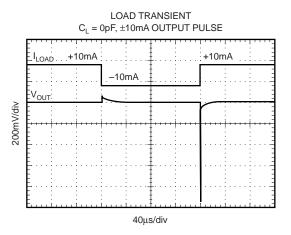


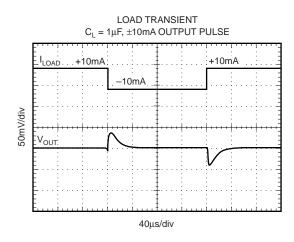
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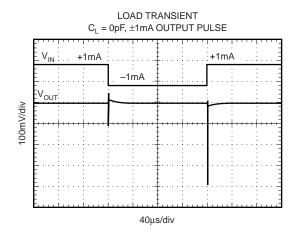
At  $T_A = +25$ °C,  $V_{IN} = +5V$  power supply, REF3125 is used for typical characteristics, unless otherwise noted.

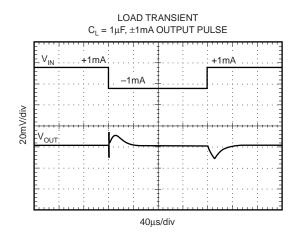












## THEORY OF OPERATION

The REF31xx is a family of series, CMOS, precision bandgap voltage references. The basic bandgap topology is shown in Figure 1. Transistors  $Q_1$  and  $Q_2$  are biased such that the current density of  $Q_1$  is greater than that of  $Q_2$ . The difference of the two base-emitter voltages,  $Vbe_1-Vbe_2$ , has a positive temperature coefficient and is forced across resistor  $R_1$ . This voltage is gained up and added to the base-emitter voltage of  $Q_2$ , which has a negative temperature coefficient. The resulting output voltage is virtually independent of temperature.

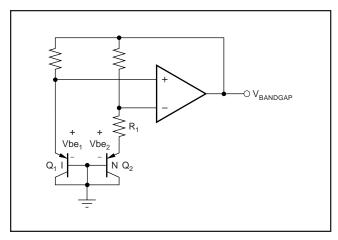


FIGURE 1. Simplified Schematic of Bandgap Reference.

## APPLICATION INFORMATION

The REF31xx does not require a load capacitor and is stable with any capacitive load. Figure 2 shows typical connections required for operation of the REF31xx. A supply bypass capacitor of  $0.47\mu F$  is recommended.

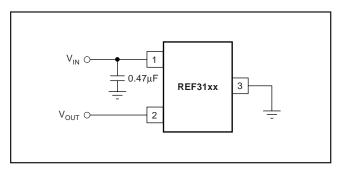


FIGURE 2. Typical Connections for Operating REF31xx.

#### SUPPLY VOLTAGE

The REF31xx family of references features an extremely low dropout voltage. With the exception of the REF3112, which has a minimum supply requirement of 1.8V, these references can be operated with a supply of only 5mV above the output voltage in an unloaded condition. For loaded conditions, a typical dropout voltage versus load is shown in the typical curves.

The REF31xx features a low quiescent current, which is extremely stable over changes in both temperature and supply. The typical room temperature quiescent current is

 $100\mu A$ , and the maximum quiescent current over temperature is just  $135\mu A$ . The quiescent current typically changes less than  $2\mu A$  over the entire supply range, as shown in Figure 3.

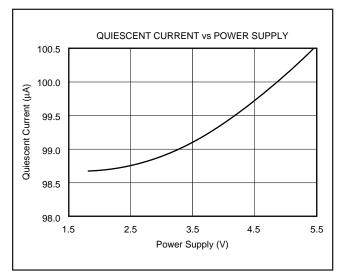


FIGURE 3. Supply Current vs Supply Voltage.

Supply voltages below the specified levels can cause the REF31xx to momentarily draw currents greater than the typical quiescent current. This can be prevented by using a power supply with a fast rising edge and low output impedance.

#### THERMAL HYSTERESIS

Thermal hysteresis for the REF31xx is defined as the change in output voltage after operating the device at 25°C, cycling the device through the specified temperature range, and returning to 25°C. It can be expressed as:

Where:  $V_{HYST}$  = Thermal hysteresis

 $V_{\text{PRE}}$  = Output voltage measured at 25°C pretemperature cycling

 $V_{POST}$  = Output voltage measured after the device has been cycled through the specified temperature range of -40°C to +125°C and returned to 25°C.

#### **TEMPERATURE DRIFT**

The REF31xx is designed to exhibit minimal drift error, defined as the change in output voltage over varying temperature. The drift is calculated using the "box" method which is described by the following equation:

The REF31xx features a typical drift coefficient of 5ppm from 0°C to 70°C—the primary temperature range for many applications. For the industrial temperature range of –40°C to 125°C, the REF31xx family drift increases to a typical value of 10ppm.



#### **NOISE PERFORMANCE**

Typical 0.1Hz to 10Hz voltage noise can be seen in the Typical Characteristic Curve, 0.1 to 10Hz Voltage Noise. The noise voltage of the REF31xx increases with output voltage and operating temperature. Additional filtering may be used to improve output noise levels, although care should be taken to ensure the output impedance does not degrade the AC performance.

#### LONG-TERM STABILITY

Long-term stability refers to the change of the output voltage of a reference over a period of months or years. This effect lessens as time progresses, as is shown by the long-term stability curves. The typical drift value for the REF31xx is 70ppm from 0-1000 hours. This parameter is characterized by measuring 30 units at regular intervals for a period of 1000 hours.

#### LOAD REGULATION

Load regulation is defined as the change in output voltage due to changes in load current. The load regulation of the REF31xx is measured using force and sense contacts as pictured in Figure 4. The force and sense lines reduce the impact of contact and trace resistance, resulting in accurate measurement of the load regulation contributed solely by the REF31xx. For applications requiring improved load regulation, force and sense lines should be used.

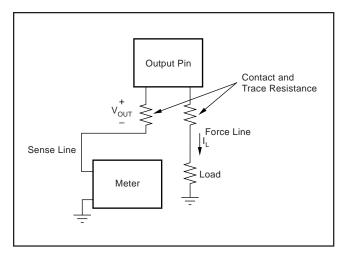


FIGURE 4. Accurate Load Regulation of REF31xx.

## **APPLICATION CIRCUITS**

#### **Negative Reference Voltage**

For applications requiring a negative and positive reference voltage, the REF31xx and OPA703 can be used to provide a dual supply reference from a ±5V supply. Figure 5 shows the REF3125 used to provide a ±2.5V supply reference voltage. The low drift performance of the REF31xx complement the low offset voltage and low drift of the OPA703 to provide an accurate solution for split-supply applications.

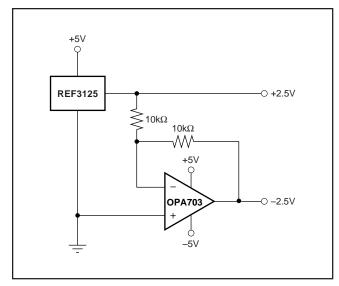


FIGURE 5. REF3125 Combined with OPA703 to Create Positive and Negative Reference Voltages.

#### DATA ACQUISITION

Data acquisition systems often require stable voltage references to maintain accuracy. The REF31xx family features stability and a wide range of voltages suitable for most microcontrollers and data converters. Figure 6, Figure 7, and Figure 8 show basic data acquisition systems.

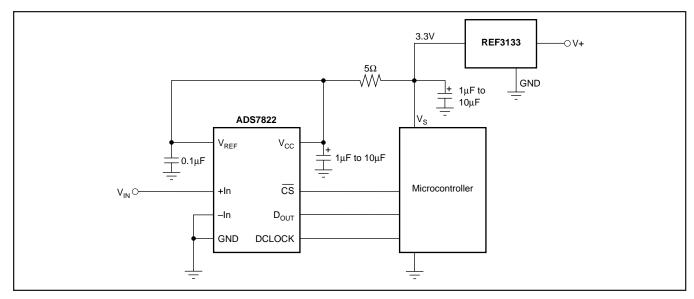


FIGURE 6. Basic Data Acquisition System 1.

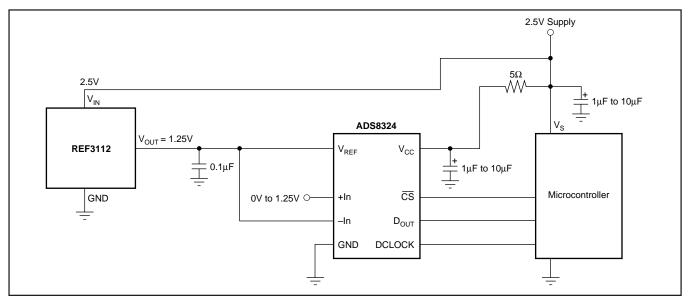


FIGURE 7. Basic Data Acquisition System 2.

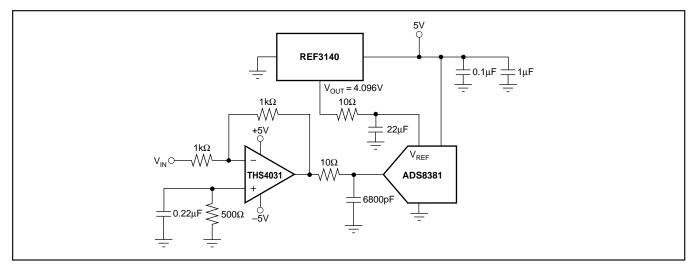


FIGURE 8. REF3140 Provides an Accurate Reference for Driving the ADS8381.



## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
REF3112AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3112AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3112AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3112AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3120AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3120AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3120AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3120AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3125AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3125AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3125AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3125AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3130AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3130AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3130AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3130AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3133AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3133AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3133AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3133AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3140AIDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3140AIDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3140AIDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
REF3140AIDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

 $<sup>^{(1)}</sup>$  The marketing status values are defined as follows:



#### PACKAGE OPTION ADDENDUM

11-Dec-2006

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**PACKAGE MATERIALS INFORMATION** 

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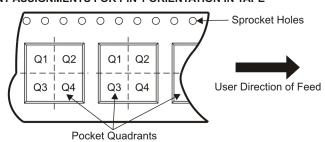
## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

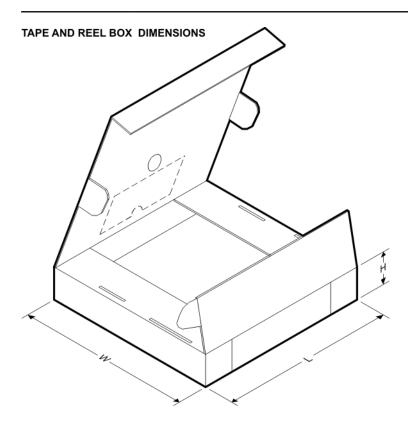


\*All dimensions are nominal

"All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
REF3112AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3112AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3120AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3120AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3125AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3125AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3130AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3130AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3133AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3133AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3140AIDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
REF3140AIDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3

**PACKAGE MATERIALS INFORMATION** 

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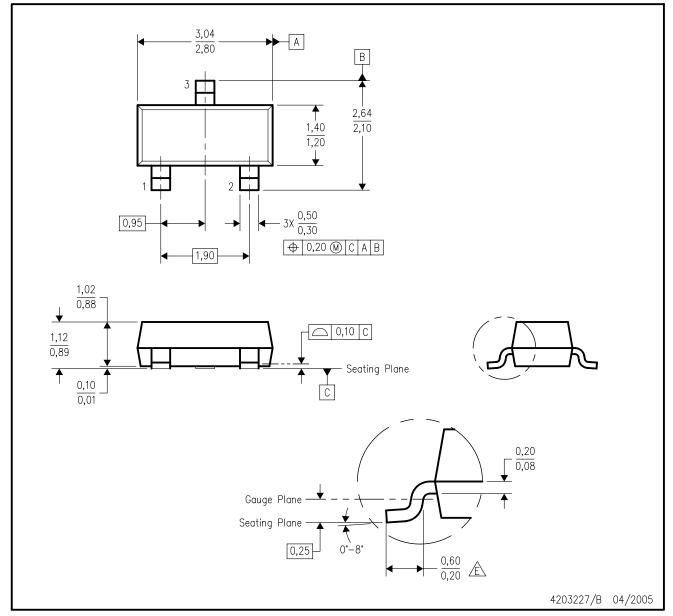


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
REF3112AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF3112AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF3120AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF3120AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF3125AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF3125AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF3130AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF3130AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF3133AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF3133AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
REF3140AIDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
REF3140AIDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0

## DBZ (R-PDSO-G3)

## PLASTIC SMALL-OUTLINE



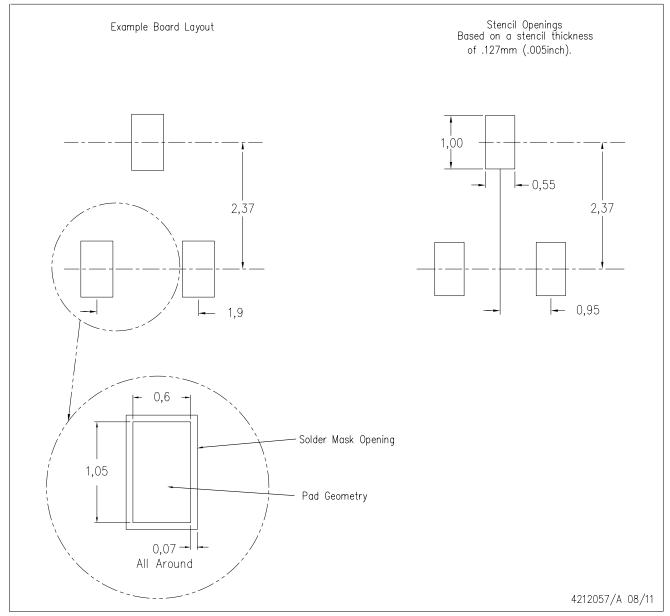
NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Lead dimensions are inclusive of plating.
- D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
- Falls within JEDEC TO-236 variation AB, except minimum foot length.



# DBZ (R-PDSO-G3)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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